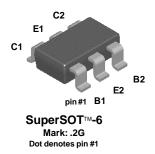


FMBA56



PNP Multi-Chip General Purpose Amplifier

This device is designed for general purpose amplifier applications at collector currents to 300 mA. Sourced from Process 73.

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V _{CES}	Collector-Emitter Voltage	80	V	
V _{CBO}	Collector-Base Voltage	80	V	
V _{EBO}	Emitter-Base Voltage	4.0	V	
I _C	Collector Current - Continuous	500	mA	
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.

 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

 3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

Thermal Characteristics T_A = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units	
		FMBA56		
P _D	Total Device Dissipation	700	mW	
	Derate above 25°C	5.6	mW/°C	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient 180		°C/W	

PNP Multi-Chip General Purpose Amplifier

(continued)

ctric			

TA = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
OFF CHAI	RACTERISTICS						
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage*	$I_C = 1.0 \text{ mA}, I_B = 0$	80			V	
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_E = 0$	80			V	
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 100 \mu A, I_C = 0$	4.0			V	
I _{CEO}	Collector-Cutoff Current	$V_{CE} = 60 \text{ V}, I_{B} = 0$			0.1	μΑ	
I _{CBO}	Collector-Cutoff Current	$V_{CB} = 80 \text{ V}, I_{E} = 0$			0.1	μΑ	
ON CHAR	ACTERISTICS DC Current Gain	I _C = 10 mA, V _{CE} = 1.0 V	100			<u> </u>	
		$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$	100				
$V_{\text{CE(sat)}}$	Collector-Emitter Saturation Voltage	$I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$			0.25	V	
V _{BE(on)}	Base-Emitter On Voltage	$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$			1.2	V	
SMALL SIGNAL CHARACTERISTICS							
f _T	Current Gain - Bandwidth Product	$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V},$ f = 100 MHz	50			MHz	

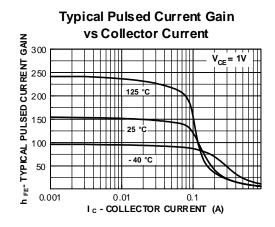
^{*}Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

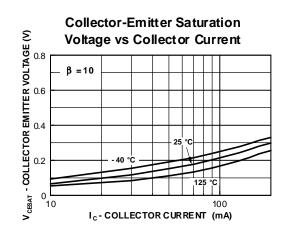
NOTE: All voltages (V) and currents (A) are negative polarity for PNP transistors.

Spice Model

PNP (Is=12.27p Xti=3 Eg=1.11 Vaf=100 Bf=91.63 Ne=1.531 Ise=12.27p Ikf=1.009 Xtb=1.5 Br=1.287 Nc=2 Isc=0 Ikr=0 Rc=.6 Cjc=48.28p Mjc=.5615 Vjc=.75 Fc=.5 Cje=106.7p Mje=.5168 Vje=.75 Tr=496.3n Tf=865.8p Itf=.2 Vtf=2 Xtf=.8 Rb=10)

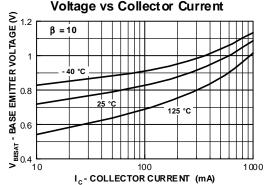
Typical Characteristics





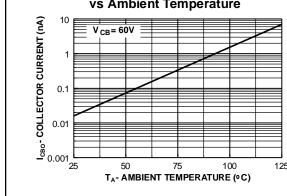
Typical Characteristics (continued)



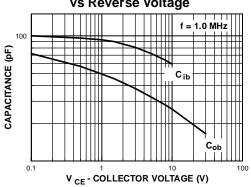


Base Emitter ON Voltage vs

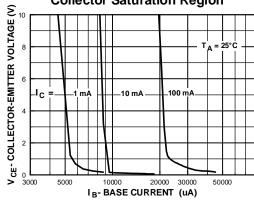
Collector-Cutoff Current vs Ambient Temperature



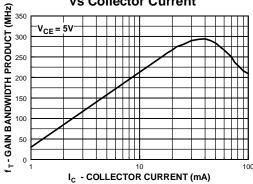
Input and Output Capacitance vs Reverse Voltage



Collector Saturation Region



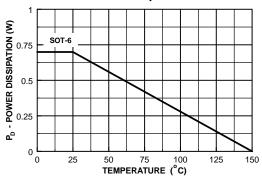
Gain Bandwidth Product vs Collector Current



PNP Multi-Chip General Purpose Amplifier (continued)

Typical Characteristics (continued)





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